AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows:

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Please **amend** the paragraph beginning on line 14 to read as follows:

~~FIG. 3 is a~~FIGS. 3A and 3B are schematic perspective ~~view~~views of a package module shown in FIG. 2.

Please **amend** the paragraph beginning on line 15 to read as follows:

~~FIG. 4 is A~~FIGS. 4A and 4B are schematic sectional ~~view~~views of a package module shown in FIG. 2.

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Please **amend** the paragraph beginning on line 25 and bridging page 10 to read as follows:

The housing 310 is provided with a fan module 320, which rotates a built-in cooling fan to generate airflow and compulsorily cools cooling fins ~~164~~164A of a heat sink ~~160~~160A, which will be described later. The fan module 320 has a power section (not shown), and a propeller section (not shown) fixed onto the power section. The power section may use any structure known in the art, which typically includes a rotary shaft, a bearing around the rotary shaft, a bearing house, a magnet for a motor, etc., and a detailed description thereof will be omitted. The

propeller section includes a number of angled, isogonally or non-isogonally arranged rotors, which have a predetermined size. The power section and the propeller section may or may not be separable.

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Please **amend** the paragraph beginning on line 10 to read as follows:

As shown in FIGS. 5 and 6, which will be described later, the LSI 102 is an exoergic circuit element soldered onto the package board 110 by bumps 104 as terminals, and the resin underfill 106 that is usually used for a flip chip (or a chip that has bumps) is filled between the LSI 102 and the package board ~~104~~110 to seal the bumps 104 and maintain connection reliability. Here, FIG. 5 is a schematic sectional view showing a relationship between the stiffener 150 and the LGA socket, while FIG. 6 is its variation. FIGS. 2 to 4 may use the structure shown in FIG. 5 or FIG. 6.

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Please **amend** the paragraph beginning on line 14 to read as follows:

Referring to FIG. 4, the first pressure mechanism 180 serves to compress one of the heat sink ~~1660~~160 and the stiffener 150 against the other, and exemplarily includes four spring clamp bolts in the instant embodiment. The first pressure mechanism 180 may press the heat sink 160 against the stiffener 150 through the top of the heat sink 160, like the first pressure mechanism 180A shown in FIG. 4A, or press the stiffener against the heat sink 160 via sectionally convex

holes 152B provided in the stiffener 150, like the first pressure mechanism 180B shown in FIG. 4B. The structure shown in FIG. 4B is preferable to maintain the heat radiation efficiency of the heat sink 160 since it does not reduce the area of the fins 164 of the heat sink 160. The hole 152 projects from the package board 110 to the front in FIG. 4B, and the spring clamp bolt is detachable from the first pressure mechanism even after the stiffener 150 is attached to the printed circuit board 200.